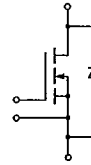
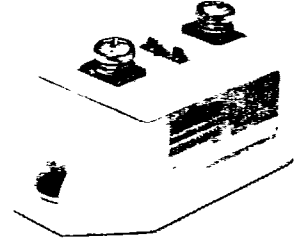


SEMITRANS® M
Power MOSFET Modules
SKM 191 F

T-39-15



Absolute Maximum Ratings			
Symbol	Conditions ¹⁾	Values	Units
V _{DS}		1000	V
V _{DGR}	R _{GS} = 20 kΩ	1000	V
I _D		28	A
I _{DM}		110	A
V _{GS}		± 20	V
P _D		700	W
T _J , T _{stg}		-55 ... +150	°C
V _{isol}	AC, 1 min, 200 μA	2 500	V
humidity	DIN 40 040	Class F	
climate	DIN IEC 68 T.1	55/150/56	
Inverse Diode			
I _F = - I _D		28	A
I _{FM} = - I _{DM}		110	A

Characteristics					
Symbol	Conditions ¹⁾	min.	typ.	max.	Units
V _{(BR)DSS}	V _{GS} = 0, I _D = 0,25 mA	1000	-	-	V
V _{GS(th)}	V _{GS} = V _{DS} , I _D = 1 mA	2,1	3,0	4,0	V
I _{DSS}	V _{GS} = 0, } T _J = 25 °C V _{DS} = 1000 V } T _J = 125 °C	-	50	250	μA
I _{GSS}	V _{GS} = 20 V, V _{DS} = 0	-	10	100	nA
R _{DS(on)}	V _{GS} = 10 V, I _D = 18 A	-	380	420	mΩ
g _{fs}	V _{DS} = 25 V, I _D = 18 A	15	22	-	S
C _{CHC}	per MOSFET	-	-	160	pF
C _{iss}	V _{GS} = 0 V _{DS} = 25 V f = 1 MHz	-	22	30	nF
C _{oss}		-	1	1,5	nF
C _{rss}		-	0,36	0,5	nF
L _{DS}		-	-	20	nH
t _{d(on)}	V _{DD} = 500 V I _D = 18 A V _{GS} = 10 V R _{GS} = 3,3 Ω	-	60	-	ns
t _r		-	30	-	ns
t _{d(off)}		-	350	-	ns
t _f		-	60	-	ns
Inverse Diode					
V _{SD}	I _F = 60 A, V _{GS} = 0	-	1,1	1,4	V
t _{rr}	T _J = 25 °C ²⁾	-	300	-	ns
	T _J = 150 °C ²⁾	-	500	-	ns
Q _{rr}	T _J = 25/150 °C ²⁾	-	1,8/13	-	μC
I _{RRM}	T _J = 25/150 °C ²⁾	-	12/28	-	A
Thermal Characteristics					
R _{thjc}		-	-	0,18	°C/W
R _{thch}	M ₁ , surface 10 μm	-	-	0,05	°C/W

Mechanical Data					
M ₁	to heatsink, SI Units	4	-	6	Nm
	to heatsink, US Units	35	-	53	lb.in.
M ₂	for terminals, SI Units	2,5	-	3,5	Nm
	for terminals, US Units	22	-	24	lb.in.
a		-	-	5x9,81	m/s ²
w		-	-	150	g
Case	→ page B 6 - 69	D 15			

¹⁾ T_{case} = 25 °C, unless otherwise specified.

²⁾ I_F = - I_D, V_R = 100 V, - di_F/dt = 100 A/μs

Features

- N Channel, enhancement mode
- Fast inverse diodes
- Short internal connections avoid oscillations
- Switching kW's in less than 1 μs
- Isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearances and creepage distances
- UL recognized, file no. E 63 532

Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- DC choppers
- Resonant and welding inverters
- Induction heaters
- AC motor drives
- Laser power supplies
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.

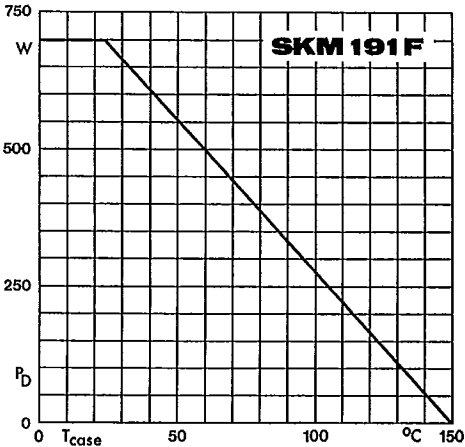


Fig. 1 Rated power dissipation vs. temperature

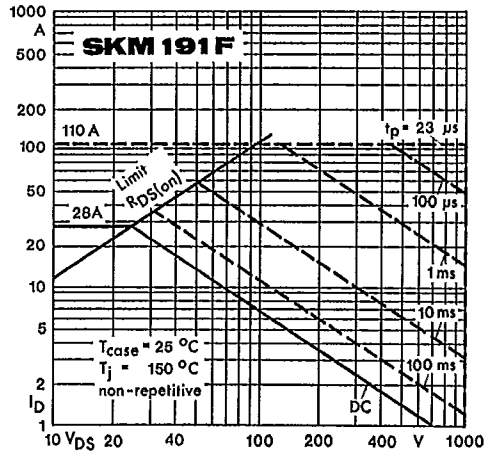


Fig. 2 Maximum safe operating area

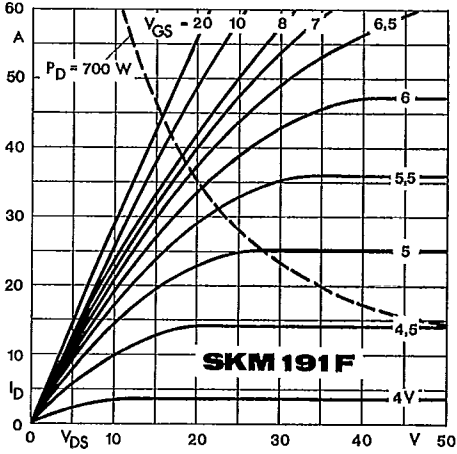


Fig. 3 Output characteristic

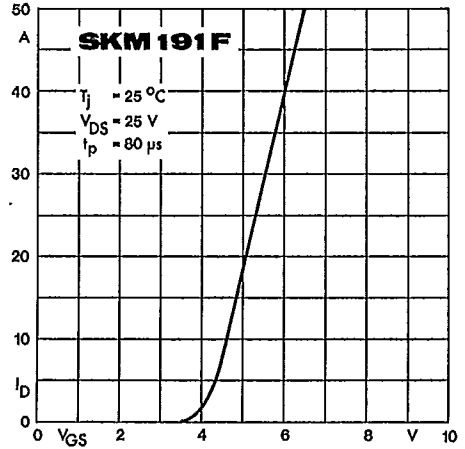


Fig. 4 Transfer characteristic

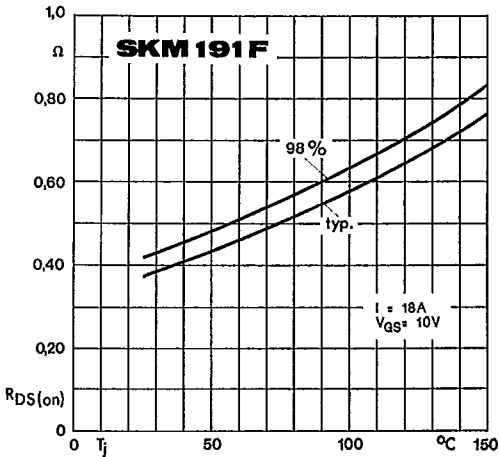


Fig. 5 On-resistance vs. temperature

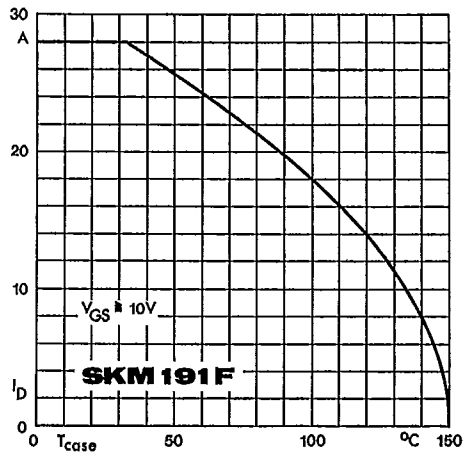


Fig. 6 Rated current vs. temperature

T-39-15

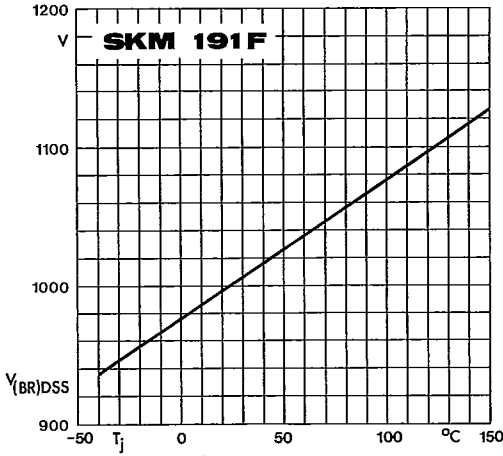


Fig. 7 Breakdown voltage vs. temperature

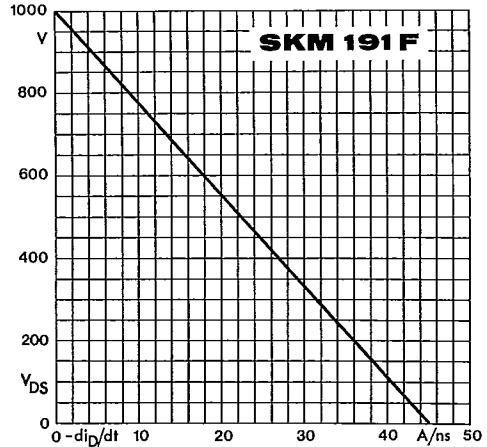


Fig. 8 Drain-source voltage derating

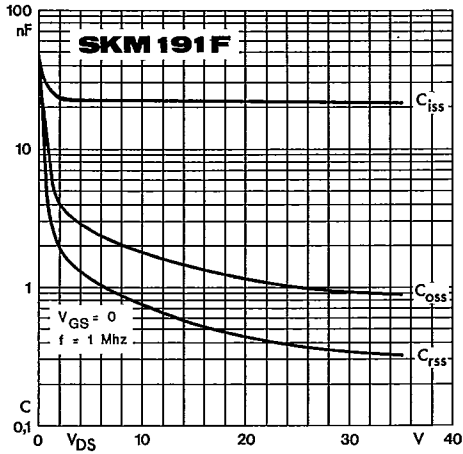


Fig. 9 Capacitances vs. drain-source voltage

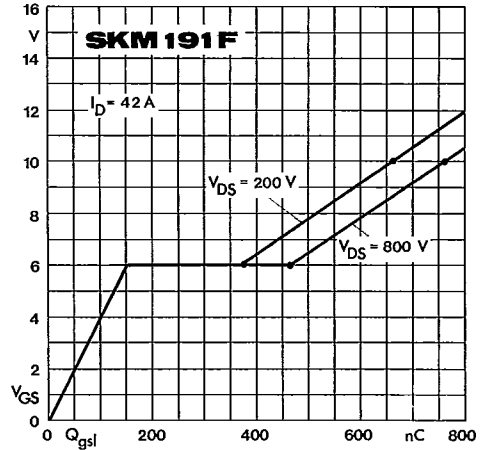


Fig. 10 Gate charge characteristic

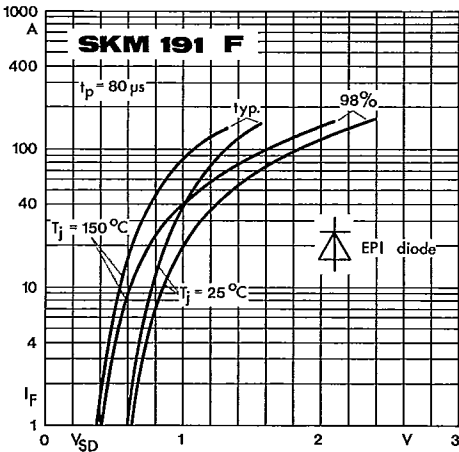


Fig. 11 Diode forward characteristic

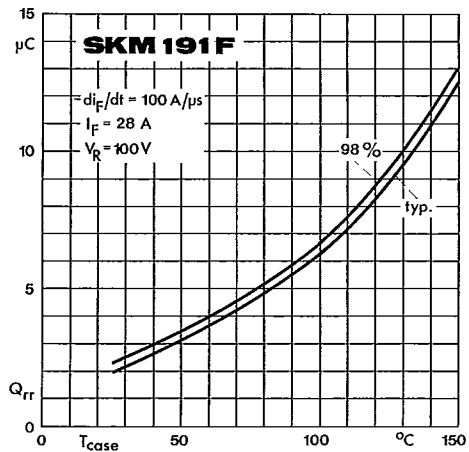


Fig. 12 Diode recovered charge

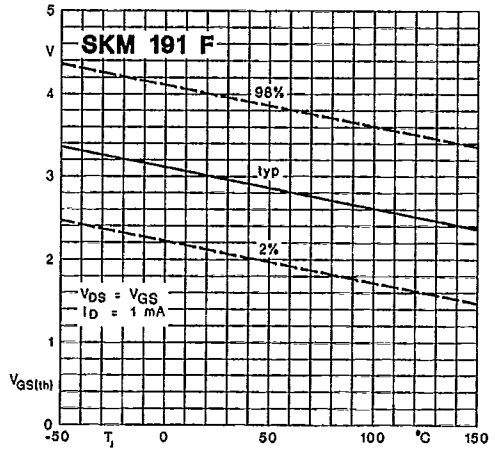


Fig. 14 Gate-source threshold voltage

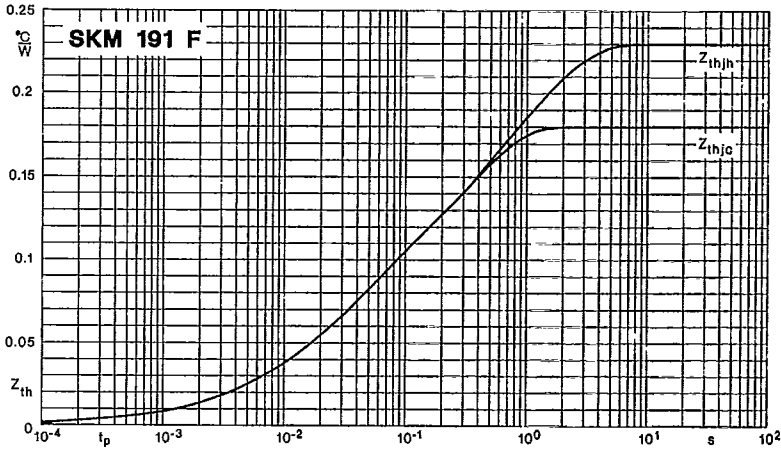


Fig. 51 Transient thermal impedance

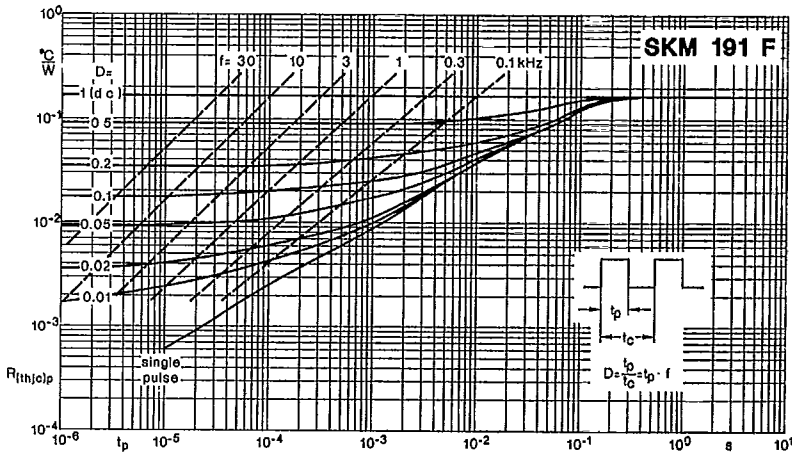


Fig. 52 Thermal impedance under pulse conditions